Timing performance of a digital SiPM prototype Studies with a fast injection laser

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HELMHOLTZ

dSiPM design overview

The concept of a digital silicon photomultiplier

Schematic structure of a p⁺/n-well SPAD in 150 nm CMOS [1] \rightarrow









metal shield

STI n⁺ STI

n-well

guard

ring

pitch size p⁺

active size-

n-well

deep n-well

p-sub

metal shield

STI n⁺

guard

ring

n-well

ST





pixel detectors

DESY digital SiPM prototype

Designed in 150 nm LFoundry CMOS process

Matrix:

- 32×32 pixels
- $70 \times 76 \ \mu m^2$ pixel pitch



~2.5 mm

DESY dSiPM reference: I. Diehl et al. JINST 19 (2024) P01020

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- Four parallel $20 \times 20 \ \mu m^2$ SPADs in each pixel

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Readout:

- Frame-based
- Full binary hitmaps
- Hit pattern recognition
- Pixel masking (with disabling bias on masked pixels)
- Fine hit timestamping via 12-bit TDC (bin size ~77 ps)



DESY dSiPM reference: I. Diehl et al. JINST 19 (2024) P01020

How timing works on the chip

Timestamping mechanism and quadrants

- Each pixel is connected to a shared **time-to-digital converter** (TDC) (located on the **periphery of each quadrant**, 4 total)
- First pixel to fire within each frame triggers the TDC of the quadrant it's in
- Thus, up to 4 timestamps are set for each frame (1 per quadrant)



In the following measurements the masking feature is used to ensure that timestamps only come from a known pixel

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manufacturing variation: real bin size = ~95 ps

Timing measurements

Timing performance @ minimum-ionizing particle detection

A story of peculiar things in the test beam results

Test-beam campaign @ DESY II:

chip characterization via direct m.i.p. detection (5 GeV e^{-}) In-pixel hitmaps for m.i.p. detection at a testbeam







Pixel layout \rightarrow

Test beam studies: F. Feindt et al. NIMA 1064 (2024) 169321 Thesis by S. Lachnit (2024)

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The measurements leading to these results have been performed at the Test Beam Facility 7 at DESY Hamburg (Germany), a member of the Helmholtz Association (HGF)

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Finding 1:

sub-100 ps is reached, but: for a fraction of events, significantly slower response is observed (**few ns**)

In-pixel hitmaps for m.i.p. detection at a testbeam



All events



Pixel layout \rightarrow

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Finding 2:

slow response occurs when a particle track crosses the chip at a **SPAD edge**

Hypothesis:

this effect is caused by avalanches being preceded by drift

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Laserbox

and how to measure timing resolution with it

Pulsed lasers

are great for charge injection:

- micrometer aim precision
- controllable trigger
- high repetition rate
- tunable intensity

Measurement scheme:

- DAQ+control via Caribou [1]
- laser trigger pulses in sync with readout frames

PiLas 672 nm injection laser pulse duration ~ **50 ps** trigger jitter < 5 ps spot size ~ 10 µm Low intensity **Control board** low-level chip interfaces dSiPM Motorized stages +cooling to aim and focus SoC + FPGA the laser DAQ software data handling

Propagation delay



- Additional delay for pixels in the matrix centre, as signals need to propagate to the periphery
- This delay can be quantified with a grain of exactly 1 TDC bin
- Results are used as an lookup table to compensate for propagation delay e.g. in the testbeam

In-pixel laser characterization xy-scan



- 1. Laser is triggered synchronously with the frame clock \rightarrow always the same ToA expected
- 2. Accumulate multiple frames to get the *timing residual distribution*
- 3. Repeat for all *xy*

In-pixel laser characterization

xy-scan



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In-pixel timing (1)

Time residual structure



In-pixel timing (2) SPAD center / SPAD edge variations





In-pixel timing (3)

ToA fit results

Per-point fits for this region \rightarrow







- Stable performance in the SPAD centres \rightarrow instant fast (~50 ps) avalanches
- Fraction of slower (~ns) events \rightarrow charges drifting to the avalanche region
 - Becomes more significant when the laser is aimed at a SPAD edge



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Use cases that require simultaneous spatial and temporal resolution

[1] <u>H. Sadrozinski et al. Rep. Prog. Phys. 81 (2018) 026101</u>

Use cases that require simultaneous spatial and temporal resolution

High-energy physics



High-granularity timing, e.g. 4D-tracking [1]

M.I.P. detection

[1] H. Sadrozinski et al. Rep. Prog. Phys. 81 (2018) 026101

Use cases that require simultaneous spatial and temporal resolution

High-energy physics



Use cases that require simultaneous spatial and temporal resolution



Conclusions

Timing performance of a novel dSiPM prototype studied

at a test beam and with a fast injection laser

- Timing resolution is characterized
 - ~50 ps timing resolution within SPADs
 - This is *total* (sensor + front-end) resolution
 - Timing performance deteriorates at the sensitive area edges
- Laser and test beam results are in agreement
- Design expectations reached*

Thank you!



Scintillator-coupled dSiPM: G. Vignola et al. NIMA 1069 (2024) 169985

Backup (1)







Backup (4) Pixel schematics



Backup (5)

Intrinsic SPAD temporal performance



Figure 8.16: Signal TOA as a function of the overvoltage for analogue pixel/SPAD test structures.